INTEGRATED CIRCUITS



Product specification File under Integrated Circuits, IC02 March 1986



HILIP

TDA1082

GENERAL DESCRIPTION

The TDA1082 is a monolithic integrated circuit driving east-west correction of colour tubes in television receivers. The circuit can be used for class-A and class-D operation and incorporates the following functions:

- differential input amplifier
- squaring stage
- differential output amplifier with driver stage
- protection stage with threshold
- · switching off the correction during flyback
- voltage stabilizer

QUICK REFERENCE DATA

Supply voltage (pin 1)	V _P	typ.	12	V
Current consumption	Ι _Ρ	typ.	17	mA
Total power dissipation	P _{tot}	max.	600	mW
Operating ambient temperature range	T _{amb}		0 to + 70	°C
Collector voltage drift external transistor	ΔV_{C}	typ.	0,7	V

PACKAGE OUTLINE

16-lead DIL; plastic (SOT38); SOT38-1; 1996 November 19.

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Limiting values in accordance with the Absolute Maximum System (IEC 134)

Supply voltage (pin 1)	VP	max.	16	V
Output current (pin 15)	$-I_O$	max.	50	mA
Total power dissipation	P _{tot}	max.	600	mW
Storage temperature range	T _{stg}	–25 to	o + 150	°C
Operating ambient temperature range	T _{amb}	0 to	+ 70	°C
Voltages				
with respect to ground (pin 2)		min.	max.	
Pins 1, 5, 7, 8, 9, 12, 13 and 16		0	16	V
Pins 3 and 4		0	-	V
Pins 10, 11 and 15		0	5	V
Currents				
Pins 3, 4 and 6		_	5	mA
Pin 14		0	1,5	mA
Pins 15 and 16 (-I _{15 and} +I ₁₆)		0	50	mA

CHARACTERISTICS

 V_P = 12 V (range 10,5 to 14 V); T_{amb} = 25 °C; measured in circuit Fig.1 with colour tube A66-500X; unless otherwise specified

Supply

Voltage range	VP	10,5	to	14	V
Voltage peak value	V _{PM}	max.		15	V
Current range	I _P	11	to	30	mA
Current typical value	Ι _Ρ	typ.		17	mA
Sawtooth signal (pin 10 or 11)					
Input voltage d.c. value	Vi	typ.		2,5	V
Input resistance	R _i	typ.		5,6	kΩ
		<		7,0	kΩ
Correcting signals (pin 13)					
Input voltage d.c. value	V ₁₃	typ.		0,6	V
Input current	I ₁₃	typ.		0,5	mA
Flyback keying (pin 3)					
Input current range	I ₃	0,05	to	5	mA
Peak value, d = 5%	l ₃	typ.		20	mA
Threshold (pin 14)					
Input voltage at $I_{14} = 200 \ \mu A$					
for switching off the driver stage	Vi	typ.		8	V
		7,2	to	8,8	V

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Output stage (pin 6)					
Generator current	I ₆	typ.		1	mA
Flyback differential amplifier (pin 5)					
D.C. value output voltage	V_5	typ.		6	V
Output resistance	R_5	typ.		5,6	kΩ
Squaring stage (pin 7)					
D.C. value output voltage	V ₇	typ.		6	V
Peak to peak value output voltage	V _{7(p-p)}	typ.		1,5	V
Output resistance	R7	5,6	to	9,4	kΩ
		typ.		7,5	kΩ
Correction trapezoidal deformation (pins 9 and 12)					
D.C. voltage	V _{9, 12}	typ.		5	V
Output resistance	R _{9, 12}	typ.		7,5	kΩ
Driver output (pin 15)					
Output current	$-I_{15}$	<		50	mA
Drift of d.c. collector voltage					
Of external transistor in closed loop					
T_{amb} = 15 to 70 °C; V_{CO} = 8 V	ΔV_{C}	typ.		0,7	V

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PACKAGE OUTLINE

DIP16: plastic dual in-line package; 16 leads (300 mil); long body



1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

(OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE
\	/ERSION	IEC	JEDEC	EIAJ	PROJECTION	1330E DATE
:	SOT38-1	050G09	MO-001AE			-92-10-02 95-01-19

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SOT38-1

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SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

Soldering by dipping or by wave

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ($T_{stg max}$). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

Repairing soldered joints

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	

Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.